軍商兩用貨品及技術出口管制清單及一般軍用貨品清單

新、舊版修正對照與翻譯

編列說明

- 1. 軍商兩用貨品及技術出口管制清單列入第一項,一般軍用貨品清單列入第二項。
- 2. 本對照表列出下列情況:
 - a. 中文有增/刪語詞,原意有所變動者;
 - b. 舊版無、新版新增之內容;
 - c. 舊版有、新版刪除之內容;
- 3. 本對照表未列出下列情況,但已於檔案中進行修正,與現行公布英文版本一致:
 - a. 標點符號變動、專有名詞單引號或雙引號變動、CAS 編號前加註 CAS 字樣者;
 - b. 英文編輯改變,未改變原有內容意義者;
 - C. 排版方式變更,未改變原有內容意義者;
 - d. 既有版本的錯字與誤植。
- 4. 為符合國際文體指南(2015年版),英文版本以逗號分隔整數與小數,以空間分隔表明千位整數。

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第一項:軍商兩用貨品及技術出口管制清單修正對照表(黃色標示是修正差異)

修正條目	現行內容	擬修正/新增內容	現行內容英譯	擬修正/新增內容英譯
專用術語定義	"補償系統"(第6類)主要由非向量 感測器與1個或以上參考感測器(如 "向量磁力計")所組成,同時配有可 減輕平台上剛體旋轉噪音之軟體。	無修正	"Compensation systems" (6) consist of the primary scalar sensor, one or more reference sensors (e.g., vector "magneto-meters") together with software that permit reduction of rigid body rotation noise of the platform.	"Compensation systems" (6) consist of the primary scalar sensor, one or more reference sensors (e.g., vector "magnetometers") together with software that permit reduction of the rigid body rotation noise of the platform.
專用術語定義	"擴散結合"(第 1、2、9 類)係指以 將至少2個分離之固態金屬物結合成 為單一物體,其結合力與其中強度較 弱者相同,其主要機制為透過接口處 原子的相互擴散。	少2個分離之固態金屬物結合成為單 一物體,其結合力與其中強度較弱者	"Diffusion bonding" (1 2 9) means a solid state joining of at least two separate pieces of metals into a single piece with a joint strength equivalent to that of the weakest material, wherein the principal mechanism is interdiffusion of atoms across the interface.	"Diffusion bonding" (1 2) means a solid state joining of at least two separate pieces of metals into a single piece with a joint strength equivalent to that of the weakest material, wherein the principal mechanism is interdiffusion of atoms across the interface.
專用術語定義	"固有磁梯度計"(第6類)係指單一磁場梯度感測元件與相關之電子裝置,其輸出即磁場梯度之一測量。 說明:參照"磁力梯度計"。	無修正	"Intrinsic Magnetic Gradiometer" (6) is a single magnetic field gradient sensing element and associated electronics the output of which is a measure of magnetic field gradient. N.B. See also "magnetic gradiometer".	"Intrinsic Magnetic Gradiometer" (6) is a single magnetic field gradient sensing element and associated electronics the output of which is a measure of magnetic field gradient. N.B. See also "Magnetic Gradiometer".
專用術語定義	"磁梯度計"(第6類)係指儀器用於 偵測本身以外來源之磁場空間變化。 此等儀器由多個 "磁力計"及相關電 子裝置組成,其輸出為磁場梯度之一 測量值。 說明:參照 "固有磁梯度計"。	無修正	"Magnetic Gradiometers" (6) are instruments designed to detect the spatial variation of magnetic fields from sources external to the instrument. They consist of multiple "magnetometers" and associated electronics the output of which is a measure of magnetic field gradient. N.B. See also "intrinsic magnetic gradiometer"	"Magnetic Gradiometers" (6) are instruments designed to detect the spatial variation of magnetic fields from sources external to the instrument. They consist of multiple "magnetometers" and associated electronics the output of which is a measure of magnetic field gradient. N.B. See also "Intrinsic Magnetic Gradiometer".

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專用術語定義		"程式"(第 <mark>6</mark> 類)係指執行某種程序 之系列指令,或可轉換為可由電子電 腦執行之形式。	"Program" (2 6) means a sequence of instructions to carry out a process in, or convertible into, a form executable by an electronic computer.	"Program" (6) means a sequence of instructions to carry out a process in, or convertible into, a form executable by an electronic computer.
1C006.b.	 b. 以下列任一為其主要成分之潤滑 材料: 1. 苯或烷基苯之醚類或硫醚類或其 混合物,含有2個以上醚或硫醚官能 基或其混合;或 2. 在298 K(25 ℃)下測量,動黏度小 於5,000 mm2/s(5,000 centistokes)之氟 化聚矽氧流體; 	其混合物,含有2個以上醚或硫醚官 能基或其混合為其主要成分之潤滑材	 b. Lubricating materials containing, as their principal ingredients, any of the following: 1. Phenylene or alkylphenylene ethers or thio-ethers, or their mixtures, containing more than two ether or thio-ether functions or mixtures thereof; or 2. Fluorinated silicone fluids with a kinematic viscosity of less than 5 000 mm2/s (5 000 centistokes) measured at 298 K (25 °C); 	b. Lubricating materials containing, as their principal ingredients, phenylene or alkylphenylene ethers or thio-ethers, or their mixtures, containing more than two ether or thio-ether functions or mixtures thereof;
1E201	依照一般技術註解,為"使用" 1A002、1A007、1A202、1A225至 1A227、1B201、 <mark>1B225至1B234</mark> 、 1C002.b.3.或 b.4.、1C010.b.、1C202、 1C210、1C216、1C225至1C241或 1D201所述貨品之"技術"	依照一般技術註解,為"使用" 1A002、1A007、1A202、1A225至 1A227、1B201、 <mark>1B225至1B235</mark> 、 1C002.b.3.或 b.4.、1C010.b.、1C202、 1C210、1C216、1C225至1C241或 1D201所述貨品之"技術"	"Technology" according to the General Technology Note for the "use" of goods specified in 1A002, 1A007, 1A202, 1A225 to 1A227, 1B201, 1B225 to 1B234, 1C002.b.3. or .b.4., 1C010.b., 1C202, 1C210, 1C216, 1C225 to 1C241 or 1D201.	"Technology" according to the General Technology Note for the "use" of goods specified in 1A002, 1A007, 1A202, 1A225 to 1A227, 1B201, 1B225 to 1B235, 1C002.b.3. or .b.4., 1C010.b., 1C202, 1C210, 1C216, 1C225 to 1C241 or 1D201.
2B006.b.1	 在0至0.2mm ~量測範圍 ~之 中,解析度等於或小於(優於)0.2μm 之 *非接觸式測量系統 ~; 	 在0至0.2mm²量測範圍²之中,²解析度⁵等於或小於(優於)0.2 μm之¹非接觸式測量系統²; 	1. 'Non-contact type measuring systems' with a resolution equal to or less (better) than 0,2 μm within a measuring range up to 0,2 mm;	1. 'Non-contact type measuring systems' with a 'resolution' equal to or less (better) than 0,2 µm within a measuring range up to 0,2 mm;

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2B006.b 技術註解3.b.	 b. 整個量測範圍內之解析度為 0.2 nm 或以下(優於);及 	b. 整個量測範圍內之 <mark>)</mark> 解析度 <mark>)</mark> 為 0.2 nm 或以下(優於); 及	b.A resolution over their full scale of 0,200 nm or less (better); and	b. A 'resolution' over their full scale of 0,200 nm or less (better); and
2B006.b	無	技術註解: 就項目 2B006.b.而言,'解析度'是量具 的最小增量; 在數字儀器上,最低有 效位。	無	Technical Note: For the purposes of 2B006.b., 'resolution' is the least increment of a measuring device; on digital instruments, the least significant bit
2B206.c.2	2. 標準溫度和標準壓力下,能夠 <mark>在</mark> ±1 K(±1°C)溫度下維持至少 12 小時, 具下列所有特性:	 標準溫度和標準壓力下,能夠超過 ±1 K (±1°C)溫度下維持至少 12 小時,具下列所有特性: 	2. Capable of maintaining, for at least 12 hours, at a temperature of \pm 1 K (\pm 1 °C); around a standard temperature and standard pressure, all of the following:	2. Capable of maintaining, for at least 12 hours, over a temperature range of \pm 1 K (\pm 1°C); around a standard temperature and standard pressure, all of the following:
2B206.c.2.a.	a. <mark>解析度</mark> 在全尺度情況下等於或優 於 0,1 μm;及	 a. 解析度 在全尺度情況下等於 或優於 0,1 μm;及 技術註解: 就 2B206.c.2.a.目的,'解析度'是量具 的最小增量;在數字儀器上,最低有 效位。 	a. A <mark>resolution</mark> over their full scale of 0,1 μm or better; and	 a. A 'resolution' over their full scale of 0,1 μm or better; and Technical Note: For the purpose of 2B206.c.2.a. 'resolution' is the least increment of a measuring device; on digital instruments, the least significant bit.

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2B352.b 技術註解 2	 培育室保持設備包括具備硬質壁 之一次性使用之培育室。 	 就 2B352.b.目的,培育室保持設備 包括具備硬質壁之一次性使用之培育 室。 	2. Cultivation chamber holding devices include single-use cultivation chambers with rigid walls.	2. For the purposes of 2B352.b. cultivation chamber holding devices include single-use cultivation chambers with rigid walls
2D352	無	專為項目 2B352.i.所述的核酸組合和 合成而設計的"軟件",能夠設計及 建構序列數據和功能性遺傳物質。	無	"Software" specially designed for nucleic acid assemblers and synthesisers specified in 2B352.i., that is capable of designing and building functional genetic elements from digital sequence data.
2E003.b.1.c	c. `直接作用液壓成形´;	c. `直接作用液壓成形´; 技術註解: `直接作用液壓成形´係指一種變形 過程,使用充滿液體之彈性囊袋直接 與工作物件接觸。	c. 'Direct-acting hydraulic pressing';	c. 'Direct-acting hydraulic pressing'; Technical Note: 'Direct-acting hydraulic pressing' is a deformation process which uses a fluid-filled flexible bladder in direct contact with the workpiece.
2E003.b.2.	 2. 包含於下列程序方法或參數,且用 於控制之技術資料: a. 鋁合金、鈦合金或 "超合金" 之 "超 塑性成形": 1. 表面預處理; 2. 應變率; 3. 溫度; 4. 壓力; 	 - 删除; 註解: 有關燃氣渦輪發動機和部件的金屬加 工製造工藝的"技術",請參閱 9E003 和軍品管制。 	 2. Technical data consisting of process methods or parameters as listed below used to control: a. "Superplastic forming" of aluminium alloys, titanium alloys or "superalloys":	 2. Not used; N.B. For "technology" for metal-working manufacturing processes for gas turbine engines and components, see 9E003 and the Military Goods Controls.

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	 b. "超合金"或鈦合金之、擴散結 合": 1. 表面預處理; 2. 溫度; 3. 壓力; c. 鋁合金或鈦合金之、直接作用液 壓成形 : 1. 壓力; 2. 循環時間; d. 鈦合金、鋁合金或、超合金"之、熱均壓緻密化 : 1. 溫度; 2. 壓力; 3. 循環時間; 技術註解: 1. 「直接作用液壓成形、係指一種變形過程,使用充滿液體之彈性囊袋直接與工作物件接觸。 2.、熱均壓緻密化、係指在密閉腔室中以超過375K(102°C)加壓鑄造之過程,利用不同介質(氣體、液體、固態粒子等)在各方向產生相同力量,以減少或消除鑄造物之內在空隙。 		 "superalloys" or titanium alloys: 1. Surface preparation; 2. Temperature; 3. Pressure; c. 'Direct-acting hydraulic pressing'of aluminium alloys or titanium alloys: 1. Pressure; 2. Cycle time; d. 'Hot isostatic densification' of titanium alloys, aluminium alloys or "superalloys": 1. Temperature; 2. Pressure; 3. Cycle time; Technical Notes: 1. 'Direct-acting hydraulic pressing' is a deformation process which uses a fluid-filled flexible bladder in direct contact with the workpiece. 2. 'Hot isostatic densification' is a process of pressurising a casting at temperatures exceeding 375 K (102 °C) in a closed cavity through various media (gas, liquid, solid particles, etc.) to create equal force in all directions to reduce or eliminate internal voids in the casting 	
第2類 表-沉積技術- 註解	 第2類不包括實心機翼之單一步 驟包覆滲入 "技術"。 	無修正	10. Category 2 does not include "technology" for single-step pack cementation of solid airfoils.	10. Category 2 does not include "technology" for single-step pack cementation of solid aerofoils.

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3A.註解 1	註解1:3A001或3A002中除 3A001.a.3.至3A001.a.10.、3A001.a.12. 至3A001.a.14.所述以外之設備與零 件管制狀況,專為其他設備所設計或 具有與其他設備相同功能特徵者,由 其他設備之管制狀況所決定。	註解1:3A001或3A002中除 3A001.a.3.至3A001.a.10.、3A001.a.12. 至3A001.a.14,或3A001.b.12.所述以 外之設備與零件管制狀況,專為其他 設備所設計或具有與其他設備相同功 能特徵者,由其他設備之管制狀況所 決定。	Note 1: The control status of equipment and components described in 3A001 or 3A002, other than those described in 3A001.a.3. to 3A001.a.10., or 3A001.a.12. to 3A001.a.14., which are specially designed for or which have the same functional characteristics as other equipment is determined by the control status of the other equipment	Note 1: The control status of equipment and components described in 3A001 or 3A002, other than those described in 3A001.a.3. to 3A001.a.10., or 3A001.b.12. to 3A001.a.14., or 3A001.b.12., which are specially designed for or which have the same functional characteristics as other equipment is determined by the control status of the other equipment.
3A001.b 技術註解	b. 微波或毫米波項目,如下: 技術註解: 就 3A001.b.目的,飽和參數峰值輸出 功率亦可以為產品數據表中所提及之 輸出功率、飽和輸出功率、最大輸出 功率、峰值輸出功率,或包絡線峰值 輸出功率。	無修正	 b. Microwave or millimetre wave items as follows: Technical Notes: For purposes of 3A001.b., the parameter peak saturated power output may also be referred to on product data sheets as output power, saturated power output, maximum power output, peak power output, or peak envelope power output. 	b. Microwave or millimetre wave items as follows: Technical Note: For the purposes of 3A001.b., the parameter peak saturated power output may also be referred to on product data sheets as output power, saturated power output, maximum power output, peak power output, or peak envelope power output.
3A001.b.4.b.1.	 在超過 6.8 GHz 最高至 8.5 GHz 且 包含 8.5 GHz 之任何頻率,其飽和峰 值輸出功率大於 70 W (48.54 dBm); 	 在超過 6.8 GHz 最高至 8.5 GHz 且 包含 8.5 GHz 之任何頻率,其飽和峰 值輸出功率大於 70 W (48.45 dBm); 	1. A peak saturated power output greater than 70 W (48,54 dBm) at any frequency exceeding 6,8 GHz up to and including 8,5 GHz;	1. A peak saturated power output greater than 70 W (48,45 dBm) at any frequency exceeding 6,8 GHz up to and including 8,5 GHz;
3A001.b.11.e.	e. 任何頻率變動超過 2.2 GHz,合成 頻率範圍超過 37 GHz 但未超過 <mark>90</mark> GHz 時,低於 100 μs;	e. 任何頻率變動超過 2.2 GHz,合成 頻率範圍超過 37 GHz 但未超過 <mark>75</mark> GHz 時,低於 100 μs;	e. Less than 100 μs for any frequency change exceeding 2,2 GHz within the synthesised frequency range exceeding 37 GHz but not exceeding 90 GHz; or	e. Less than 100 μs for any frequency change exceeding 2,2 GHz within the synthesised frequency range exceeding 37 GHz but not exceeding 75 GHz;
3A001.b.11.f.	f. 刪除;或	f. 任何頻率變動超過 5.0 GHz, 合成 頻率範圍超過 75 GHz 但未超過 90 GHz 時,低於 100 μs; 或	f. Not used;	f. Less than 100 μs for any frequency change exceeding 5,0 GHz within the synthesised frequency range exceeding 75 GHz but not exceeding 90 GHz; or

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3A002.c.2.	 "訊號分析儀"具有平均顯示雜訊 位準(DNAL)在任何地方低於(優 於)-150 dBm/Hz,其頻率超過43.5 GHz 但不超過90 GHz; 	無修正	2. "Signal analysers" having Displayed Average Noise Level (DANL) less (better) than -150 dBm/Hz anywhere within the frequency range exceeding 43,5 GHz but not exceeding 90 GHz;	2. "Signal analysers" having a Displayed Average Noise Level (DANL) less (better) than -150 dBm/Hz anywhere within the frequency range exceeding 43,5 GHz but not exceeding 90 GHz;
3A002.d.3.e.	e. 在頻率超過 37 GHz,但不超過 <mark>90</mark> GHz 的條件下,頻率變化超過 2.2 GHz 時之切換時間小於 100 μs;	e. 在頻率超過 37 GHz,但不超過 <mark>75</mark> GHz 的條件下,頻率變化超過 2.2 GHz 時之切換時間小於 100 μs;	e. Less than 100 μs for any frequency change exceeding 2,2 GHz within the frequency range exceeding 37 GHz but not exceeding 90 GHz;	e. Less than 100 μ s for any frequency change exceeding 2,2 GHz within the frequency range exceeding 37 GHz but not exceeding 75 GHz; or
3A002.d.3.g.	無	g. 在頻率超過75 GHz,但不超過90 GHz 的條件下,頻率變化超過5.0 GHz 時之切換時間小於100 μs;	無	g. Less than 100 µs for any frequency change exceeding 5,0 GHz within the frequency range exceeding 75 GHz but not exceeding 90 GHz;
3A002.d.4.	4. 單邊帶(SSB)相雜訊,以 dBc/Hz 為 單位,具下列任一特性者:	無修正	4.Single sideband (SSB) phase noise, in dBc/Hz, specified as being any of the following:	4. A single sideband (SSB) phase noise, in dBc/Hz, specified as being any of the following:
3A002.d.5.c.	c. 在頻率範圍超過 37 GHz 但不超過 <mark>90</mark> GHz 情況下,超過 2.2 GHz 者;或	c. 在頻率範圍超過 37 GHz 但不超過 <mark>75</mark> GHz 情況下, 超過 2.2 GHz 者; 或 d. 在頻率範圍超過 75 GHz 但不超過 90 GHz 情況下, 超過 5.0 GHz 者; 或	5. An 'RF modulation bandwidth' of digital baseband signals as specified by any of the following: a. Exceeding 2,2 GHz within the frequency range exceeding 4,8 GHz but not exceeding 31,8 GHz; b. Exceeding 550 MHz within the frequency range exceeding 31,8 GHz but not exceeding 37 GHz; c. Exceeding 2,2 GHz within the frequency range exceeding 37 GHz but not exceeding 90 GHz; or	 5. An 'RF modulation bandwidth' of digital baseband signals as specified by any of the following: a. Exceeding 2,2 GHz within the frequency range exceeding 4,8 GHz but not exceeding 31,8 GHz; b. Exceeding 550 MHz within the frequency range exceeding 31,8 GHz but not exceeding 37 GHz; c. Exceeding 2,2 GHz within the frequency range exceeding 37 GHz; c. Exceeding 75 GHz; or d. Exceeding 5,0 GHz within the frequency range exceeding 75 GHz but not exceeding 90 GHz; or

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3A002.d.5.d.	無	d. 在頻率範圍超過 75 GHz 但不超過 90 GHz 情況下,超過 5.0 GHz 者;或	無	d. Exceeding 5,0 GHz within the frequency range exceeding 75 GHz but not exceeding 90 GHz; or
3C001.e.	無	e. 氧化鎵 (Ga ₂ O ₃); 或	無	e. Gallium Oxide (Ga ₂ O ₃); or
3C001.f.	無	f. 鑽石	無	f. Diamond.
3E003.h.	無	h. 用於電子零件之氧化鎵基板。	無	h. Substrates of gallium oxide for electronic components.
4A003.b.	b. "數位電腦"具有 "調整尖峰效能" ("APP")超過每秒 <mark>29</mark> 加權兆(10 ¹²) 浮點運算(WT)者;	b. "數位電腦"具有 "調整尖峰效能" ("APP")超過每秒 <mark>70</mark> 加權兆(10 ¹²) 浮點運算(WT)者;	b. "Digital computers" having an "Adjusted Peak Performance" ("APP") exceeding 29 Weighted TeraFLOPS (WT);	b. "Digital computers" having an "Adjusted Peak Performance" ("APP") exceeding 70 Weighted TeraFLOPS (WT);
第5類 第1部分 5E001.d 技術註解	技術註解: 就 5E001.d.目的,飽和峰值參數輸出 功率亦可以為產品數據表中所提及之 輸出功率、飽和輸出功率、最大輸出 功率、峰值輸出功率,或包絡線峰值 輸出功率。	無修正	Technical Note: For purposes of 5E001.d., the parameter peak saturated power output may also be referred to on product data sheets as output power, saturated power output, maximum power output, peak power output, or peak envelope power output.	Technical Note: For the purposes of 5E001.d., the parameter peak saturated power output may also be referred to on product data sheets as output power, saturated power output, maximum power output, peak power output, or peak envelope power output.
第5類 第2部分 5A003.a	 a. 經設計或修改之通訊電纜系統,以 使用機械、電機或電子方法以偵測秘 密入侵者; 	無修正	a. Communications cable systems designed or modified using mechanical, electrical or electronic means to detect surreptitious intrusion;	a. Communications cable systems designed or modified to use mechanical, electrical or electronic means to detect surreptitious intrusion;
6A005.d.1.b.1	 波長小於 1,400 nm, 且平均或連續 波輸出功率超過 15 W; 	 波長小於 1,400 nm, 且平均或連續 波輸出功率超過 25 W; 	1. Wavelength of less than 1 400 nm and average or CW output power, exceeding 15W	1. Wavelength of less than 1 400 nm and average or CW output power, exceeding 25 W;
6A008.1.4. 註解	通服務´之系統、設備及零件。	註解:6A008.1.4.不管制 <mark>設計用於</mark> `船 舶交通服務´之系統、設備及零件。	Note: 6A008.1.4. does not control systems, equipment and assemblies used for 'vessel traffic service'.	Note: 6A008.1.4. does not control systems, equipment and assemblies designed for 'vessel traffic service'.
6A008. 技術註解1	 1.就 6A008.目的, [*]船用雷達[*]指在 海上、內陸水域或近海環境用於 航行 安全者。 	 1.就 6A008.目的, [~]船用雷達[~]指在 海上、內陸水域或近海環境設計用於 航行安全者。 	1. For the purposes of 6A008, 'marine radar' is a radar that is used to navigate safely at sea, inland waterways or near-shore environments	1. For the purposes of 6A008, 'marine radar' is a radar that is designed to navigate safely at sea, inland waterways or near-shore environments.

修正條目	現行內容	擬修正/新增內容	現行內容英譯	擬修正/新增內容英譯
6D003.h.1.	 1. 設計用於安裝於飛航管制中心 (ATC)之一般用途電腦上,以執行飛 航交通管制,以及能接受4個以上主 要雷達之雷達目標資料之"軟體"應 用"程式"。 	 設計用於安裝於飛航管制中心 (ATC)之一般用途電腦上,以執行飛 航交通管制,以及能接受4個以上主 要雷達之雷達目標資料之"軟體"。 	1. Air Traffic Control (ATC) "software" application "programs" designed to be hosted on general purpose computers located at Air Traffic Control centres and capable of accepting radar target data from more than four primary radars;	1. Air Traffic Control (ATC) "software" designed to be hosted on general purpose computers located at Air Traffic Control centres and capable of accepting radar target data from more than four primary radars;
7D003.e.	e. 特別設計用於"開發""主動飛行 控制系統"、直升機多軸線傳飛操或 光傳飛操控制器或直升機"環流控制 抗扭矩或環流控制方向控制系統"之 電腦輔助設計(CAD)"軟體",其"技 術"由 7E004.b.1.、7E004.b.3.至 7E004.b.5.、7E004.b.7.、7E004.b.8.、 7E004.c.1.或7E004.c.2.所管制。	無修正	e. Computer-Aided-Design (CAD) "software" specially designed for the "development" of "active flight control systems", helicopter multi-axis fly-by-wire or fly-by-light orhelicopter "circulation controlled anti-torque or circulation-controlled direction control systems", whose "technology" is specified in 7E004.b.1., 7E004.b.3. to 7E004.b.5., 7E004.b.7., 7E004.b.8., 7E004.c.1. or 7E004.c.2.	e. Computer-Aided-Design (CAD) "software" specially designed for the "development" of "active flight control systems", helicopter multi-axis fly-by-wire or fly-by-light controllers or helicopter "circulation- controlled anti-torque or circulation-controlled direction control systems", whose "technology" is specified in 7E004.b.1., 7E004.b.3. to 7E004.b.5., 7E004.b.7., 7E004.b.8., 7E004.c.1. or 7E004.c.2.
7E004.c.3. 及 技術註解	 3. 用於使用個別翼片控制之系統,包含、可變幾何機翼、旋翼。 技術註解: 、可變幾何機翼、指使用後緣襟翼或調整片、前緣襟翼或軸鼻翼,其位置 在飛行中可受控制。 	無修正	 3. Rotor blades incorporating 'variable geometry airfoils', for use in systems using individual blade control. Technical Note: 'Variable geometry airfoils' use trailing edge flaps or tabs, or leading edge slats or pivoted nose droop, the position of which can be controlled in flight. 	 3. Rotor blades incorporating 'variable geometry aerofoils', for use in systems using individual blade control. Technical Note: 'Variable geometry aerofoils' use trailing edge flaps or tabs, or leading edge slats or pivoted nose droop, the position of which can be controlled in flight.
9A004.	太空發射載具、"太空載具"、"太 空載具本體"、"太空載具酬載"、"太 空載具"裝載系統、空中發射平台或 設備及地面設備,如下:	太空發射載具、"太空載具"、"太 空載具本體"、"太空載具酬載"、"太 空載具"裝載系統、 <mark>或設備、地面設</mark> 備、空中發射平台及次軌道飛行器, 如下:	Space launch vehicles, "spacecraft", "spacecraft buses", "spacecraft payloads", "spacecraft" on-board systems or equipment, and terrestrial equipment, as follows:	Space launch vehicles, "spacecraft", "spacecraft buses", "spacecraft payloads", "spacecraft" on-board systems or equipment, terrestrial equipment, air-launch platforms and "sub-orbital craft" as follows:

修正條目	現行內容	擬修正/新增內容	現行內容英譯	擬修正/新增內容英譯
9A004.g.	g. 特別設計或改裝之 "飛行器",作 為太空發射載具之空中發射平台。	g. 特別設計或改裝之 ["] 飛行器",作 為太空發射載具之空中發射平台 <mark>或次</mark> <mark>軌道飛行器</mark> 。	g. "Aircraft" specially designed or modified to be air-launch platforms for space launch vehicles;	g. "Aircraft" specially designed or modified to be air-launch platforms for space launch vehicles or "sub- orbital craft";
9B001.c.	c. 特別設計用於製造燃氣渦輪葉 片、導片或 "葉尖覆緣" 之定向凝固 或單晶添加製造設備。	c. 設計用於 "超合金" 之定向凝固或 單晶添加製造設備。	c. Directional-solidification or single-crystal additive-manufacturing equipment, specially designed for manufacturing gas turbine engine blades, vanes or "tip shrouds".	c. Directional-solidification or single-crystal additive-manufacturing equipment, designed for "superalloys".
9B004.	 用於燃氣渦輪,並以固態結合 9E003.a.3.或 9E003.a.6.所述之 "超合金"、鈦或金屬間扇葉盤組合之工具、 壓模或夾具。 	無修正	Tools, dies or fixtures, for the solid state joining of "superalloy", titanium or intermetallic airfoil-to-disk combinations described in 9E003.a.3. or 9E003.a.6. for gas turbines.	Tools, dies or fixtures, for the solid state joining of "superalloy", titanium or intermetallic aerofoil-to-disk combinations described in 9E003.a.3. or 9E003.a.6. for gas turbines.
9B005.a 註解	註解:9B005.a.不 <mark>管制</mark> 特別設計為教 學用途,且 [、] 測試段尺寸 [、] (側面量 測)小於 250 mm 之風洞;	註解:9B005.a.不 <mark>適用於</mark> 特別設計為 教學用途,且 [、] 測試段尺寸 [、] (側面 量測)小於 250 mm 之風洞;	Note: 9B005.a. does not control wind tunnels specially designed for educational purposes and having a 'test section size' (measured laterally) of less than 250 mm.	Note: 9B005.a. does not apply to wind tunnels specially designed for educational purposes and having a 'test section size' (measured laterally) of less than 250 mm.
9E003.a.4	 4. 設計用於[、]燃氣路徑溫度[、]在 1,373 K (1,100 °C)或以上操作之非冷 卻式渦輪葉片、導片及[、]葉尖覆緣["]; 	無修正	4. Uncooled turbine blades, vanes or "tip-shrouds", designed to operate at a 'gas path temperature' of 1 373 K (1 100 °C) or more	4. Uncooled turbine blades, vanes or "tip shrouds", designed to operate at a 'gas path temperature' of 1 373 K (1 100 °C) or more;
9E003.a.5	5. 除 9E003.a.1.所述外之冷卻式渦輪 葉片、導片及 "葉尖覆緣",其設計 操作用於 燃氣路徑溫度 在 1,693 K (1,420 °C)或以上。	無修正	5. Cooled turbine blades, vanes, "tip-shrouds" other than those described in 9E003.a.1., designed to operate at a 'gas path temperature' of 1 693 K (1 420 °C) or more;	5. Cooled turbine blades, vanes, "tip shrouds" other than those described in 9E003.a.1., designed to operate at a 'gas path temperature' of 1 693 K (1 420 °C) or more;
9E003.a.6.	6. 使用固態接合之扇葉盤葉片組合;	無修正	 Airfoil-to-disk blade combinations using solid state joining; 	6. Aerofoil-to-disk blade combinations using solid state joining;

第二項:一般軍用貨品清單修正對照表

修正條目	現行內容	擬修正/新增內容	現行內容英譯	擬修正/新增內容英譯
ML4.a.	 a. 為軍事用途而特別設計之炸彈、 魚雷、手榴彈、煙霧彈、火箭、地雷、 飛彈、深水炸彈、爆破火藥,爆破裝 置、爆破工具、`焰火彈´裝置、彈 藥筒及模擬器(即可模擬上述任一物 品特徵之設備); 註解:ML4.a.包括: a. 煙霧手榴彈、縱火彈、燒夷彈及 爆炸裝置; b. 飛彈或火箭噴嘴及重返大氣層載 具之機頭尖端。 	 a.為軍事用途而特別設計之炸彈、魚 雷、手榴彈、煙霧彈、火箭、地雷、 飛彈、深水炸彈、爆破火藥,爆破裝 置、爆破工具、[×]焰火彈⁻裝置、彈 藥筒、<mark>子彈藥</mark>及模擬器(即可模擬上述 任一物品特徵之設備); 註解:ML4.a.包括: a.煙霧手榴彈、縱火彈、燒夷彈及爆 炸裝置; b.飛彈或火箭噴嘴及重返大氣層載具 之機頭尖端。 說明:ML1或ML2中指定的武器或射 擊器使用之手榴彈或霰彈筒以及為特 別彈藥設計的子彈藥,請參見ML3。 	 a. Bombs, torpedoes, grenades, smoke canisters, rockets, mines, missiles, depth charges, demolition- charges, demolition-devices, demolition-kits, "pyrotechnic" devices, cartridges and simulators (i.e. equipment simulating the characteristics of any of these items), specially designed for military use; Note ML4.a. includes: a. Smoke grenades, fire bombs, incendiary bombs and explosive devices; b. Missile or rocket nozzles and re-entry vehicle nosetips. 	 a. Bombs, torpedoes, grenades, smoke canisters, rockets, mines, missiles, depth charges, demolition-charges, demolition-devices, demolition-kits, "pyrotechnic" devices, cartridges, submunitions therefor and simulators (i.e., equipment simulating the characteristics of any of these items), specially designed for military use; Note ML4.a. includes: a. Smoke grenades, fire bombs, incendiary bombs and explosive devices; b. Missile or rocket nozzles and re-entry vehicle nosetips. N.B. For grenade or canister ammunition for weapons or projectors specified in ML1. or ML2. and submunitions specially designed for ammunition, see ML3.
ML4.b. 註解 1.a.	 a. 移動式氣體液化設備,該設備能 夠每日製造 1,000 kg 或以上之液化 氣體; 	a. 移動式氣體液化設備;	a. Mobile gas liquefying equipment capable of producing 1,000 kg or more per day of gas in liquid form;	a.Mobile gas liquefying equipment;
ML10.f. 註解	 f. 特別為 ML10.a.所述之 "航空器" 或 ML10.d.所述之航空發動機而開發 之 ` 地面設備 ´ ; 	 f. 特別為 ML10.a.所述之 "航空器" 或 ML10.d.所述之航空發動機而開發之 `地面設備´; 	f. Ground equipment specially designed for "aircraft" specified by ML10.a. or aero-engines specified by	f. Ground equipment specially designed for "aircraft" specified by ML10.a. or aero-engines specified by

修正條目	現行內容	擬修正/新增內容	現行內容英譯	擬修正/新增內容英譯
	註解:ML10.f. 包括壓力加油設備和 設計用於在促進在狹窄區域作業的 設備,包括船上的設備。	註解 1: ML10.f. 包括壓力加油設備和 設計用於在促進在狹窄區域作業的設 備,包括船上的設備。 註解 2: ML10.f.不適用於下列: 1. 牽引桿; 2. 保護墊和蓋; 3. 梯子,階梯和平台; 4. 楔子, 綁紮和捆縛設備。	ML10.d.; Note ML10.f. includes pressure refuelling equipment and equipment designed to facilitate operations in confined areas, including equipment located on board a ship.	 ML10.d.; Note 1 ML10.f. includes pressure refuelling equipment and equipment designed to facilitate operations in confined areas, including equipment located on board a ship. Note 2 ML10.f. does not apply to: 1. Towbars; 2. Protective mats and covers; 3. Ladders, steps and platforms; 4. Chocks, lashings and tie-down equipment.
ML11.a. 註解 e	e. 使用 <mark>加密程序</mark> 之數據處理保密設 備、數據保密設備及傳輸與訊號線路 保密設備;	e. 使用 <mark>加密功能</mark> 之數據處理保密設 備、數據保密設備及傳輸與訊號線路 保密設備;	e. Data processing security equipment, data security equipment and transmission and signalling line security equipment, using ciphering processes;	e. Data processing security equipment, data security equipment and transmission and signalling line security equipment, using cryptographic functionality;
ML11.b.	b. "衛星導航系統"之干擾設備及 特別為其設計之零件;	b. 經設計或修改之干擾設備,用以妨 礙 "衛星導航系統"所提供之接收、 操作或定位有效性,導航或定時服務 等之效果,及為達成此目的專門設計 之組件;	b. "Satellite navigation system" jamming equipment and specially designed components therefor;	b. Jamming equipment designed or modified to hinder the reception, operation or effectiveness of positioning, navigation or timing services provided by "satellite navigation systems", and specially designed components therefor;
ML13.b. 註解	無	註解 5: ML13.d.1.不適用於護目鏡。 說明:針對雷射護目鏡參照 ML17.o.。	無	Note 5 ML13.d.1. does not apply to protective eyewear. N.B. For laser protective eyewear, see ML17.o.

修正條目	現行內容	擬修正/新增內容	現行內容英譯	擬修正/新增內容英譯
ML15 註解 說明		說明:與"第一代影像增強管"併用 之武器瞄準器,參照 ML1、ML2 及 ML5.a.。	weapons sights incorporating	N.B. For weapon sights incorporating "first generation image intensifier tubes" see ML1., ML2. and ML5.a.